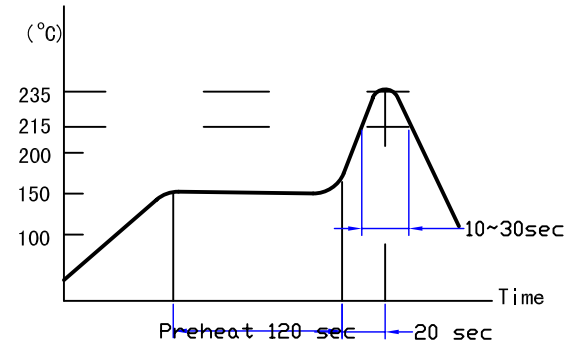


P. C. B TERMINAL POSITION



REFLOW SOLDERING CONDITIONS

No	Parts	Material	Qty	Finish	Specifications	PJ-202-4p直插 TITLE: PHONE JACK	
1	Body	PA66+30%Fider	1	94V-0	Rating: DC 12V 1A		
2	Chip Terminal	t:0.25 Cu-TI Alloy	1	Ep-Cu/Ni 1, Ag 1 (Silver Plating)	Contact Resistance: 30m ohm max	UNIT: mm	SCALE:
3	Sleeve Terminal	t:0.25 Cu-TI Alloy	1	Ep-Cu/Ni 1, Ag 1 (Silver Plating)	Insulation Resistance: 100M ohm at 500V DC	DRAWN: Aijw	DATE: 2005-12-14
4	Ring Terminal	t:0.25 Cu-TI Alloy	1	Ep-Cu/Ni 1, Ag 1 (Silver Plating)	Dielectric Strength: AC 500V for 1 Minute	CHECKED:	DATE:
5	Ring Terminal	t:0.25 Cu-TI Alloy	1	Ep-Cu/Ni 1, Ag 1 (Silver Plating)	Insertion & Extraction Force: 0.3-2.0kgf	APPROVED:	DATE:
					Life: 5.000 Cycles		
					Taping: 1.000 Pcs/Reel		
XYFW(www.cnxyfw.com)				